



● **Description:**

High current density due to double mesa technology;

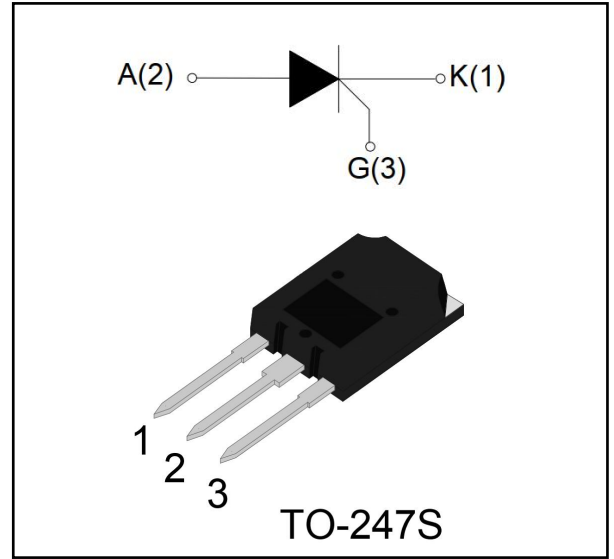
● **Applications:**

WCR75 series of silicon controlled rectifiers are specifically designed for high power switching and phase control applications.

● **Features:**

- WCR75 series are suitable for general purpose applications, a high gate sensitivity is required
- WCR75 series are non-insulated design.
- Blocking voltage to 1200/1600/1800V
- On-state RMS current to 75A
- Non-repetitive peak on-state current to 1000A

● **Absolute Maximum Ratings**



Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	Repetitive peak off-state voltage	$T_J=25^{\circ}C$	1200	1800	V
V_{RRM}	Repetitive peak Reverse voltage	$T_J=25^{\circ}C$	1200	1800	V
$I_{T(RMS)}$	RMS on-state current (all conduction angles)	Lead current limitation	-	75	A
$I_{T(av)}$	Average on-state current (half sine wave)	$T_c=80^{\circ}C$	-	70	A
I_{TSM}	Non-repetitive peak On-state current (half sine cycle, $T_J=25^{\circ}C$)	$F=50Hz, t=10ms$	-	1000	A
		$F=60Hz, t=8.3ms$	-	1150	A
I^2t	I^2t Value for fusing	$T_P=10ms$	-	5000	A^2S
di/dt	Critical rate of rise of on-state current after triggering	$I_{TM}=20A, I_G=50mA$	-	150	$A/\mu s$
I_{GM}	Peak gate current	$T_P=20\mu s, T_J=125^{\circ}C$	-	2.5	A
P_{GM}	Peak gate power		-	10	W
$P_{G(AV)}$	Average gate power dissipation		-	2.0	W
T_{STG}	Storage temperature		-40	150	$^{\circ}C$
T_J	Junction temperature		-40	125	$^{\circ}C$



● Electrical Characteristics

Symbol	Conditions	Numerical		Unit
		MIN	MAX	
I_{GT}	$V_D=12V, R_L=33\Omega$	20	100	mA
V_{GT}		1.5		V
V_{GD}	$V_D=V_{DRM}, R_L=3.3K\Omega, T_J=125^\circ C$	0.2		V
I_L	$I_T=1.2I_{GT}$	/	200	mA
I_H	$I_T=500mA$	/	150	mA
dv/dt	$V_{DM}=67\%V_{DRM}, \text{gate open}, T_J=125^\circ C$	1000	1000	V/ μs

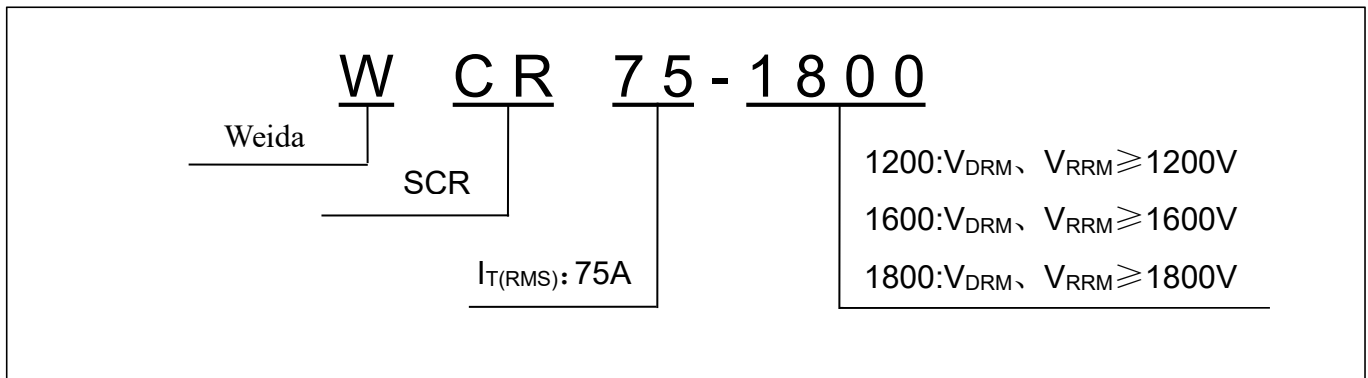
● Electrical Characteristics

Symbol	Parameter	Numerical(MAX)	Unit
V_{TM}	$I_T=100A, t_p=380\mu s$ $T_J=25^\circ C$	1.55	V
I_{DRM}	$V_D=V_{DRM}, V_R=V_{RRM}$ $T_J=25^\circ C$	50	μA
I_{RRM}		$T_J=125^\circ C$	10

● Thermal Characteristics

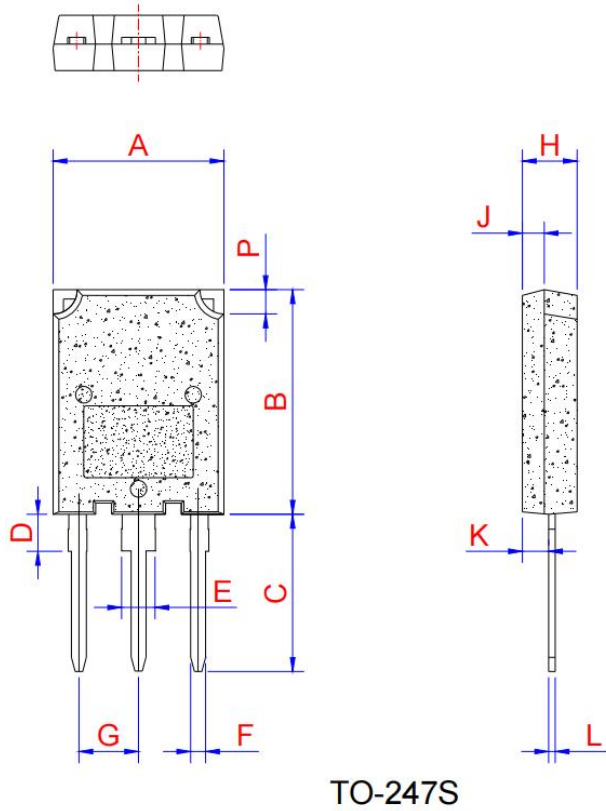
Symbol	Parameter	Numerical(MAX)	Unit
$R_{th(j-mb)}$	Thermal resistance from junction to mounting base	0.32	$^\circ C/W$

● Ordering Information





● Package Outline Dimensions



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.1		16.1	0.594		0.634
B	19.8		20.8	0.78		0.819
C	13.8		14.8	0.543		0.583
D	3.00		4.00	0.118		0.157
E	2.75		3.35	0.108		0.132
F	1.30		1.50	0.051		0.059
G	5.10		5.80	0.201		0.228
H	4.50		5.50	0.177		0.217
J	1.45		2.15	0.057		0.085
K	1.90		2.80	0.075		0.110
L	0.55		0.80	0.022		0.031
P	2.00		2.40	0.079		0.094

● Marking

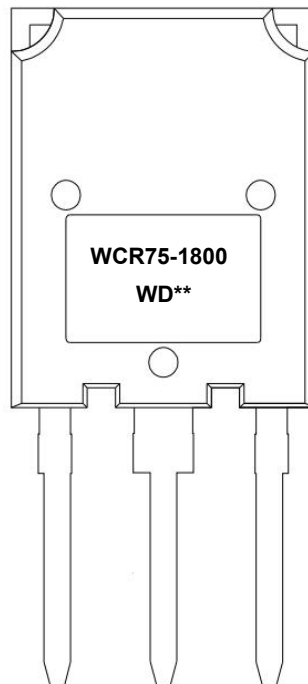




FIG.1: Maximum power dissipation versus RMS on-state current

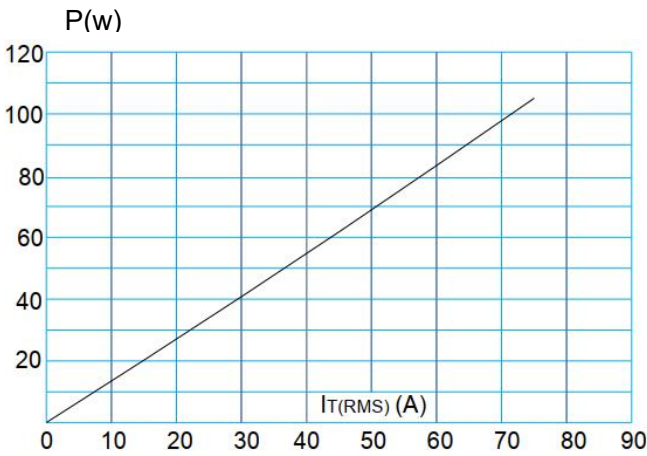


FIG.2: RMS on-state current versus case temperature

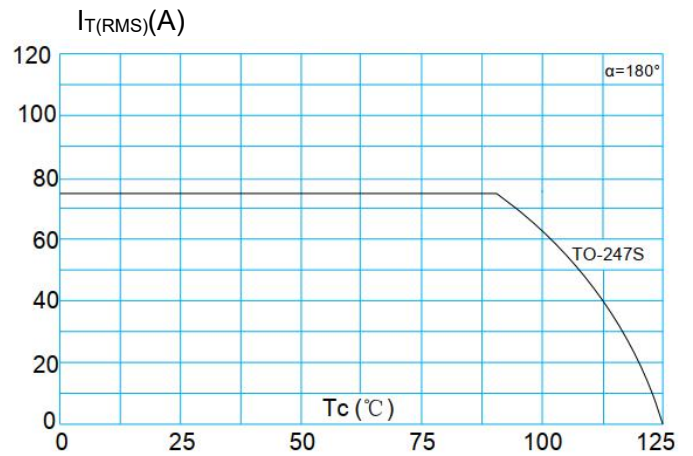


FIG.3: Surge peak on-state current versus number of cycles

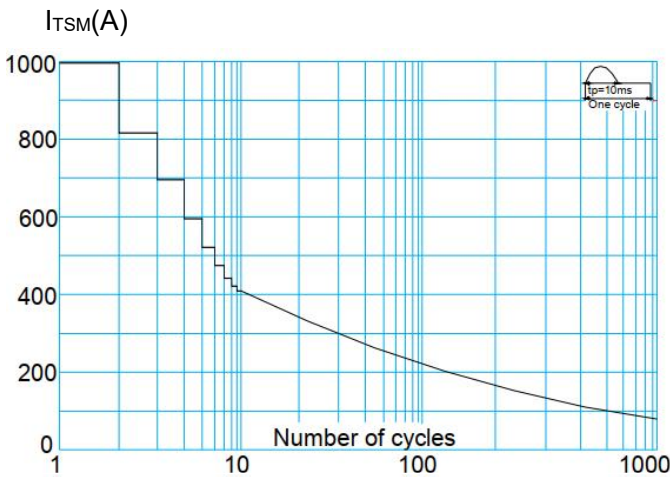


FIG.4: On-state characteristics (maximum values)

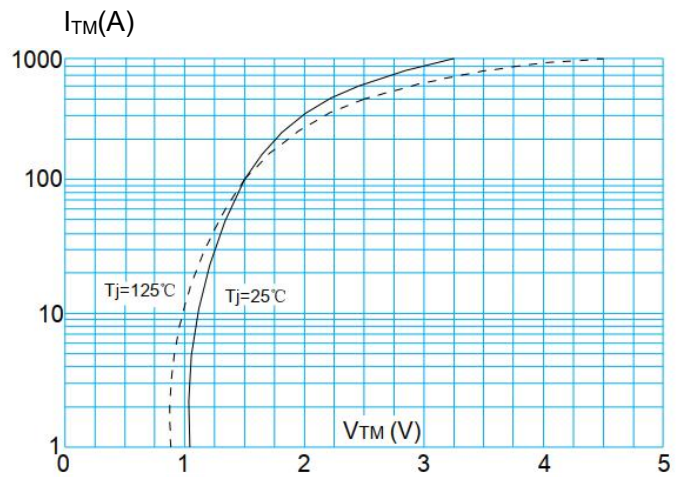


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms, and corresponding value of I²t (I - II -III:dl/dt < 50A/µs; IV:dl/dt < 10A/µs)

ITSM(A), I²t (A²s)

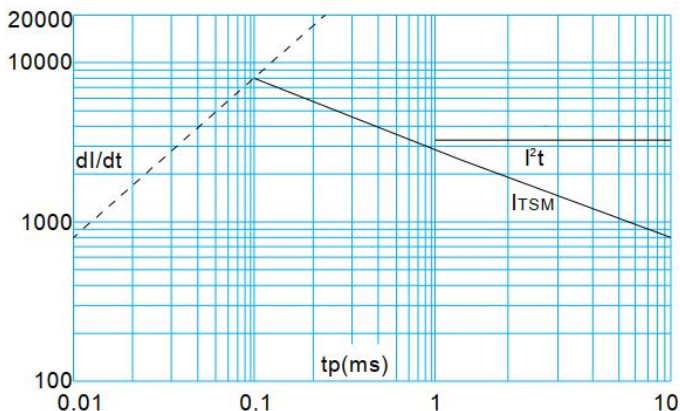
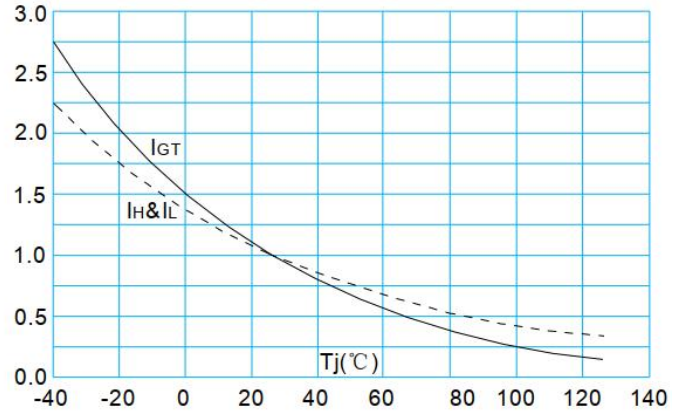


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature

IGT, IH, IL(Tj)/IGT, IH, IL(Tj=25°C)





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